

### General Description

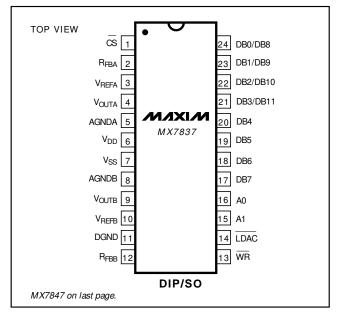
The MX7837/MX7847 are dual, 12-bit, multiplying, voltage-output digital-to-analog converters (DACs). Each DAC has an output amplifier and a feedback resistor. The output amplifier is capable of developing  $\pm 10 V$  across a  $2k\Omega$  load. The amplifier feedback resistor is internally connected to  $V_{OUT}$  on the MX7847. No external trims are required to achieve full 12-bit performance over the entire operating temperature range.

The MX7847 has a 12-bit parallel data input, whereas the MX7837 operates with a double-buffered 8-bit-bus interface that loads data in two write operations. All logic signals are level triggered and are TTL and CMOS compatible. Fast timing specifications make these DACs compatible with most microprocessors.

### **Applications**

Small Component-Count Analog Systems
Digital Offset/Gain Adjustments
Industrial Process Control
Function Generators
Automatic Test Equipment
Automatic Calibration
Machine and Motion Control Systems
Waveform Reconstruction
Synchro Applications

### Pin Configurations



#### **Features**

- Two 12-Bit Multiplying DACs with Buffered Voltage Output
- ♦ Specified with ±12V or ±15V Supplies
- ♦ No External Adjustments Required
- **♦** Fast Timing Specifications
- ♦ 24-Pin DIP and SO Packages
- ♦ 12-Bit Parallel Interface (MX7847) 8-Bit + 4-Bit Interface (MX7837)

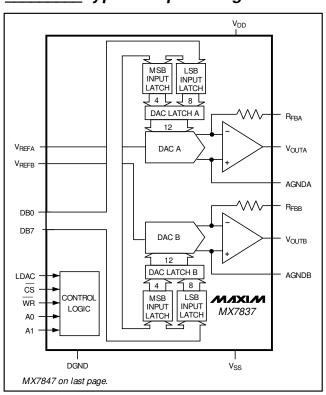
#### Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE	ERROR (LSB)
<b>MX7837</b> JN	0°C to +70°C	24 Narrow Plastic DIP	±1
MX7837KN	0°C to +70°C	24 Narrow Plastic DIP	±1/2
MX7837JR	0°C to +70°C	24 Wide SO	±1
MX7837KR	0°C to +70°C	24 Wide SO	±1/2
MX7837C/D	0°C to +70°C	Dice*	±1

#### Ordering Information continued on last page.

\* Contact factory for availability and processing to MIL-STD-883.

### Typical Operating Circuits



MIXIM

#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>DD</sub> to DGND, AGNDA, AGNDB0.3V to +17V
V <sub>SS</sub> to DGND, AGNDA, AGNDB (Note 1)+0.3V to -17V
$V_{REFA}$ , $V_{REFB}$ to AGNDA, AGNDB ( $V_{SS}$ - 0.3V) to ( $V_{DD}$ + 0.3V)
AGNDA, AGNDB to DGND0.3V to $(V_{DD} + 0.3V)$
$V_{OUTA}$ , $V_{OUTB}$ to AGNDA, AGNDB( $V_{SS}$ - 0.3V) to ( $V_{DD}$ + 0.3V)
$R_{FBA}$ , $R_{FBB}$ to AGNDA, AGNDB( $V_{SS}$ - 0.3V) to ( $V_{DD}$ + 0.3V)
Digital Inputs to DGND0.3V to $(V_{DD} + 0.3V)$
Continuous Power Dissipation ( $T_A = +70$ °C)
Narrow Plastic DIP (derate 13.33mW/°C above +70°C)1067mW
SO (derate 11.76mW/°C above +70°C)941mW
Narrow CERDIP (derate 12.50mW/°C above +70°C)1000mW

operating reinperature ranges.	
MX78_7J_/K	0°C to +70°C
MX78_7A_/B	40°C to +85°C
MX78_7SQ/TQ	
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10sec)	+300°C

Operating Temperature Ranges:

**Note 1:** If V<sub>SS</sub> is open-circuited with V<sub>DD</sub> and either AGND applied, the V<sub>SS</sub> pin will float positive exceeding the *Absolute Maximum Ratings*. If this possibility exists, a Schottky diode connected between V<sub>SS</sub> and GND ensures the maximum ratings will be observed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{DD}=11.4V~to~16.5V,~V_{SS}=-11.4V~to~-16.5V,~AGNDA=AGNDB=DGND=0V,~V_{REFA}=V_{REFB}=+10V,~R_{L}=2k\Omega,~C_{L}=100pF,~V_{OUT}~connected~to~R_{FB}~(MX7837),~T_{A}=T_{MIN}~to~T_{MAX},~unless~otherwise~noted.)~(Note~2)$ 

PARAMETER	SYMBOL		CONDITIONS		MIN	TYP	MAX	UNITS
STATIC PERFORMANCE (Note 3)								
Resolution	N				12			Bits
Dolotivo Apouropy	INL	MX78_7J/A/S					±1	LSB
Relative Accuracy	IINL	MX78_7K/B/T					±1/2	LOD
Differential Nonlinearity	DNL	Guaranteed mond	otonic				±1	LSB
			T <sub>A</sub> = +25°C				±2	
Zero-Code Offset Error		Loaded with all 0s, tempco =		MX78_7J/A			±4	mV
Zero-Code Oliset Error		±5µV/°C typ	$T_A = T_{MIN}$ to $T_{MAX}$	MX78_7K/B			±3	1111
				MX78_7S/T			±5	
			T <sub>A</sub> = +25°C	MX78_7J/A/S			±5	
Gain Error		Loaded with all 1s, tempco = ±2ppm of FSR/°C typ	IA = +25°C	MX78_7K/B/T		±2	LSB	
			T <sub>A</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>	MX78_7J/A/S			±7	
			MY	MX78_7K/B/T			±4	
REFERENCE INPUTS		•						
V <sub>REF</sub> Input Resistance					8	10	13	kΩ
V <sub>REFA</sub> , V <sub>REFB</sub> Resistance Matching						±0.5	±3	%
DIGITAL INPUTS		•						•
Input High Voltage	V <sub>INH</sub>				2.4			V
Input Low Voltage	V <sub>INL</sub>						0.8	] <b>'</b>
Input Current		Digital inputs at 0'	V and V <sub>DD</sub>				±1	μΑ
Input Capacitance (Note 4)							8	pF
ANALOG OUTPUTS	ANALOG OUTPUTS							
DC Output Impedance						0.2		Ω
Short-Circuit Current		V <sub>OUT</sub> connected t	o AGND			15		mA

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD}=11.4V~to~16.5V,~V_{SS}=-11.4V~to~-16.5V,~AGNDA=AGNDB=DGND=0V,~V_{REFA}=V_{REFB}=+10V,~R_{L}=2k\Omega,~C_{L}=100pF,\\V_{OUT}~connected~to~R_{FB}~(MX7837),~T_{A}=T_{MIN}~to~T_{MAX},~unless~otherwise~noted.)~(Note~1)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
POWER REQUIREMENTS								
V <sub>DD</sub> Range	$V_{\mathrm{DD}}$		11.4		16.5	V		
V <sub>SS</sub> Range	V <sub>SS</sub>		-11.4		-16.5	V		
Positive Supply Current	I <sub>DD</sub>	Output unloaded		5	10	mA		
Negative Supply Current	I <sub>SS</sub>	Output unloaded		4	6	mA		
	$\Delta$ Gain/ $\Delta$ V <sub>DD</sub>	$V_{DD} = 15V \pm 5\%, V_{REF} = -10V$			±0.01			
Power Cupply Pointing	ΔGain/ΔV <sub>SS</sub>	V <sub>SS</sub> = -15V ±5%, V <sub>REF</sub> = 10V			±0.01	0/ nor 0/		
Power-Supply Rejection	ΔGain/ΔV <sub>DD</sub>	$V_{DD} = 12V \pm 5\%, V_{REF} = -8.9V$			±0.01	% per %		
	ΔGain/ΔV <sub>SS</sub>	V <sub>SS</sub> = -12V ±5%, V <sub>REF</sub> = 8.9V			±0.01	]		
AC CHARACTERISTICS								
Voltage-Output Settling Time	t <sub>S</sub>	Settling time to within ±1/2LSB of final DAC value; DAC latch alternately loaded will all 0s and all 1s		4		μs		
Slew Rate				7		V/µs		
Digital-to Analog Glitch Impulse	Q	DAC latch alternately loaded with 0111 and 1000		60		nV-s		
Channel-to-Channel Isolation (VREFA to VOUTB, VREFB to VOUTA)		V <sub>REF</sub> = 20p-p, 10kHz sine wave, Alternate DAC Latch Loaded with all 0s		-95		dB		
Multiplying Feedthrough Error		V <sub>REF</sub> = 20V <sub>p-p</sub> , 10kHz sine wave, latches loaded with all 0s		-90		dB		
Unity-Gain Small-Signal Bandwidth		V <sub>REF</sub> = 100mV <sub>p-p</sub> sine wave, DAC latch loaded with all 1s		1		MHz		
Full-Power Bandwidth		$V_{REF} = 20V_{p-p}$ sine wave, DAC latch loaded with all 1s		125		kHz		
Total Harmonic Distortion	THD	V <sub>REF</sub> = 6V <sub>RMS</sub> , 1kHz, DAC latch loaded with all 1s		-88		dB		
Digital Crosstalk		Code transition from all 0s to all 1s; see <i>Typical Operating Characteristics</i> graphs		10		nV-s		
Output Noise Voltage at +25°C (0.1Hz to 10Hz)		Amplifier noise and Johnson noise of RFB		2		μV <sub>RMS</sub>		

Note 2: The analog outputs can swing to within 2.5V of the supply rails. Hence, for good linearity towards full-scale,  $|V_{REFA}|$  and  $|V_{REFB}|$  must be at least 2.5V lower than  $V_{DD}$  and  $|V_{SS}|$ . Tests done with supply voltages below  $\pm 12.5$ V are done with  $V_{REFA} = V_{REFB} = \pm 8.9$ V.

Note 3: Static performance tested at V<sub>DD</sub> = +15V, V<sub>SS</sub> = -15V. Performance over supplies guaranteed by PSRR test.

Note 4: Guaranteed by design.

#### **TIMING CHARACTERISTICS**

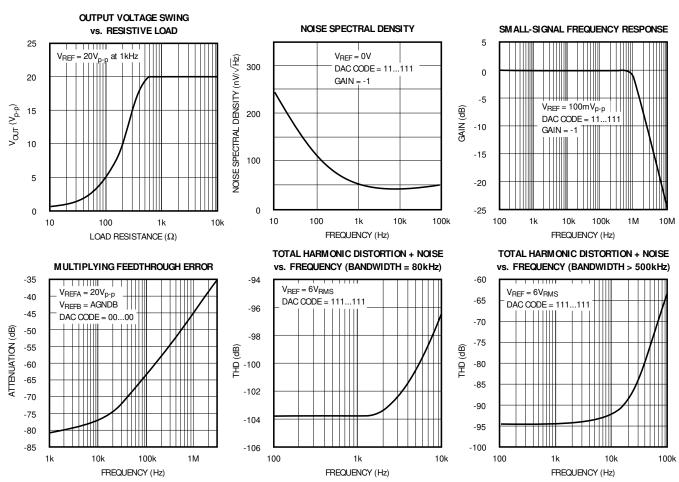
 $(V_{DD} = 11.4V \text{ to } 16.5V, V_{SS} = -11.4V \text{ to } -16.5V, \text{ AGNDA} = \text{AGNDB} = \text{DGND} = 0V, T_{A} = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$  (Note 5)

PARAMETER	SYMBOL	CONDITIONS	MX78_7J/K/A/B MIN MAX	MX78_7S/T MIN MAX	UNITS
CS to WR Setup Time	t <sub>1</sub>		0	0	ns
CS to WR Hold Time	t <sub>2</sub>		0	0	ns
WR Pulse Width	t <sub>3</sub>		80	80	ns
Data to WR Setup Time	t4		80	80	ns
Data to WR Hold Time	t <sub>5</sub>		10	10	ns
Address to WR SetupTime	t <sub>6</sub>	MX7837 only	15	15	ns
Address to WR Hold Time	t <sub>7</sub>	MX7837 only	15	15	ns
LDAC Pulse Width	t <sub>8</sub>	MX7837 only	80	80	ns

**Note 5:** All input signals are specified with  $t_R = t_F \le 5$ ns. Logic swing is 0V to 5V.

### Typical Operating Characteristics

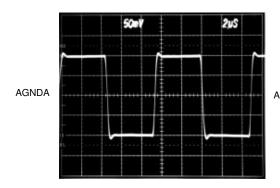
(TA = +25°C,  $V_{DD}$  = 15V,  $V_{SS}$  = -15V,  $P_L$  = 2k $\Omega$ ,  $C_L$  = 100pF, unless otherwise noted)



# Typical Operating Characteristics (continued)

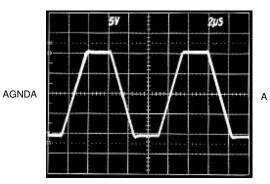
 $(T_A = +25^{\circ}C, V_{DD} = 15V, V_{SS} = -15V, R_L = 2k\Omega, C_L = 100pF, unless otherwise noted.)$ 

#### SMALL-SIGNAL PULSE RESPONSE



$$\begin{split} A &= V_{OUTA}, 50mV/div \\ TIMEBASE &= 2\mu s/div \\ V_{REFA} &= \pm 100mV \ SQUARE \ WAVE \end{split}$$

#### LARGE-SIGNAL PULSE RESPONSE



 $A = V_{OUTA}, 5V/div$   $TIMEBASE = 2\mu s/div$   $V_{REFA} = \pm 10V \; SQUARE \; WAVE$ 

### Pin Description

PIN		NAME	FUNCTION	
MX7837	MX7847	NAME	FUNCTION	
1	-	CS	Chip Select – active-low logic input	
_	1	CSA	Chip-Select Input for DAC A – active-low logic input	
2	-	R <sub>FBA</sub>	Amplifier Feedback Resistor for DAC A	
_	2	CSB	Chip-Select Input for DAC B – active-low logic input	
3	3	V <sub>REFA</sub>	Reference Input Voltage for DAC A	
4	4	Vouta	Analog Output Voltage from DAC A	
5	5	AGNDA	Analog Ground for DAC A	
6	6	$V_{\mathrm{DD}}$	Positive Power Supply	
7	7	V <sub>SS</sub>	Negative Power Supply	
8	8	AGNDB	Analog Ground for DAC B	
9	9	Voutb	Analog Output Voltage from DAC B	
10	10	V <sub>REFB</sub>	Reference Input Voltage for DAC B	
11	11	DGND	Digital Ground	
12	_	R <sub>FBB</sub>	Amplifier Feedback Resistor for DAC B	
_	12	DB11	Data Bit 11 (MSB)	
13	13	WR	Write Input – active-low logic input (MX7837); positive-edge-triggered input used with CSA and CSB (MX7847)	
14	-	LDAC	Asynchronous Load – DAC input, active-low	
_	14-24	DB10-DB0	Data Bit 10 to Data Bit 0 (LSB)	
15	-	A1	Address Input – most significant address input for input latches	
16	-	A0	Address Input – least significant address input for input latches	
17-20	-	DB7-DB4	Data Bit 7 to Data Bit 4	
21-24	-	DB3/DB11- DB0/DB8	Data Bit 3 to Data Bit 0 (LSB), or Data Bit 11 (MSB) to Data Bit 8	

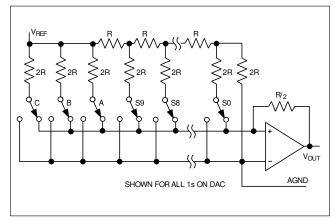


Figure 1. D/A Simplified Circuit Diagram

### Detailed Description

#### D/A Section

Figure 1 shows a simplified circuit diagram for one of the DACs and the output amplifier. Using a segmented scheme, the two MSBs of the 12-bit data word are decoded to drive the three switches (A to C). The remaining 10 bits drive the switches (S0 to S9) in a standard R-2R ladder.

Each switch (A to C) directs 1/4 of the total reference current, and the remaining current passes through the R-2R section.

The output amplifier and feedback resistor convert current to voltage as follows:  $V_{OUT} = (-D)(V_{REF})$ , where D is the fractional representation of the digital word. (D can be set from 0 to 4095/4096.)

The output amplifier is capable of developing  $\pm 10V$  across a  $2k\Omega$  load. It is internally compensated and settles to 0.01% FSR (1/2LSB) in less than 4µs.  $V_{OUT}$  on the MX7837 is not internally connected to  $R_{FB}$ .

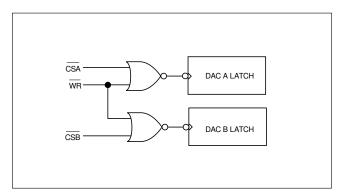


Figure 2. MX7847 Input Control Logic

# Interface Logic Information (MX7847)

Figure 2 shows the MX7847 input control logic. The device contains two independent DACs, each with its own  $\overline{\text{CS}}$  input and a common  $\overline{\text{WR}}$  input.  $\overline{\text{CSA}}$  and  $\overline{\text{WR}}$  control data loading to the DAC A latch, and  $\overline{\text{CSB}}$  and  $\overline{\text{WR}}$  control data loading to the DAC B latch. The latches are edge triggered so that input data is latched to the respective latch on  $\overline{\text{WR}}$ 's rising edge. The same data will be latched to both DACs if  $\overline{\text{CSA}}$  and  $\overline{\text{CSB}}$  are low and  $\overline{\text{WR}}$  is taken high. Table 1 shows the device control-logic truth table, and Figure 3 shows the write-cycle timing diagram.

Table 1. MX7847 Truth Table

CSA	CSB	WR	Function	
Х	Х	1	No Data Transfer	
1	1	Х	No Data Transfer	
0	1	<u>.</u>	Data Latched to DAC A	
1	0	<u>.</u>	Data Latched to DAC B	
0	0	Ā	Data Latched to Both DACs	
<u>.</u>	1	0	Data Latched to DAC A	
1	<u>.</u>	0	Data Latched to DAC B	
<u>.</u>	<u>.</u>	0	Data Latched to Both DACs	

X = Don't Care I = Rising Edge Triggered

# Interface Logic Information (MX7837)

The MX7837 input loading structure is configured for interfacing with 8-bit-wide data-bus microprocessors. Each DAC has two 12-bit latches: an input latch, and a DAC latch. Each input latch is subdivided into a least-significant 8-bit latch and a most-significant 4-bit latch. The data held in the DAC latches determines the outputs. Figure 4 shows the MX7837 input control logic, and Figure 5 shows the write-cycle timing diagram.

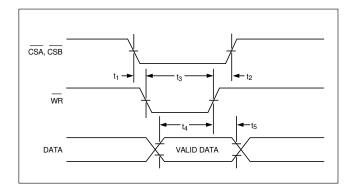


Figure 3. MX7847 Write-Cycle Timing Diagram

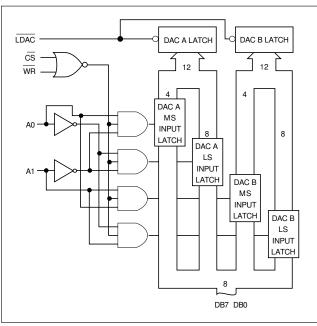


Figure 4. MX7837 Input Control Logic

CS, WR, A0, and A1 control data loading to the input latches. The eight data inputs accept right-justified data, which can be loaded to the input latches in any sequence. If LDAC is held high, loading data to the input latches will not change the analog output. A0 and A1 determine which input latch will receive the data when CS and WR are low. Table 2 shows the control logic truth table.

Table 2. MX7837 Truth Table

CS	WR	<b>A</b> 1	A0	LDAC	Function
1	Х	Χ	Х	1	No Data Transfer
Х	1	Χ	Х	1	No Data Transfer
0	0	0	0	1	DAC A LS Input Latch Transparent
0	0	0	1	1	DAC A MS Input Latch Transparent
0	0	1	0	1	DAC B LS Input Latch Transparent
0	0	1	1	1	DAC B MS Input Latch Transparent
1	1	Х	Х	0	Updated Simultaneously from the Respective Input Latches

#### X = Don't Care

The  $\overline{\text{LDAC}}$  input controls 12-bit data transfer from the input latches to the DAC latches. When  $\overline{\text{LDAC}}$  is taken low, both DAC latches (thus, both analog outputs) are updated simultaneously. When  $\overline{\text{LDAC}}$  is low, the DAC latches are transparent; DAC data is latched on the rising edge of  $\overline{\text{LDAC}}$ . The  $\overline{\text{LDAC}}$  input is asynchronous

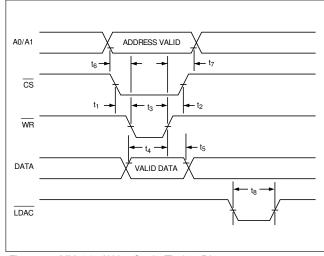


Figure 5. MX7837 Write-Cycle Timing Diagram

and independent of  $\overline{WR}$ . This is useful in many applications, especially in updating multiple MX7837s simultaneously. However, be careful when exercising  $\overline{LDAC}$  during a write cycle; if an  $\overline{LDAC}$  operation overlaps a  $\overline{CS}$  and  $\overline{WR}$  operation, invalid data may be latched to the output. To avoid this,  $\overline{LDAC}$  must remain low after  $\overline{CS}$  or  $\overline{WR}$  have returned high for a period equal to or greater than  $t_8$ , the minimum  $\overline{LDAC}$  pulse width.

#### Unipolar Binary Operation

Figure 6 shows DAC A (MX7837/MX7847) connected for unipolar binary operation. Similar connections apply for DAC B. When  $V_{IN}$  is an AC signal, the circuit performs 2-quadrant multiplication. Table 3 shows the code table for this circuit. On the MX7847, the  $R_{FB}$  feedback resistor is internally connected to  $V_{OUT}$ .

Table 3. Unipolar Code Table

DAC Latch Contents MSB LSB	Analog Output, V <sub>OUT</sub>
1111 1111 1111	$-V_{\text{IN}} \times \left(\frac{4095}{4096}\right)$
1000 0000 0000	$-V_{IN} \times \left(\frac{2048}{4096}\right) = -\frac{1}{2}V_{IN}$
0000 0000 0001	$-V_{IN} \times \left(\frac{1}{4096}\right)$
0000 0000 0000	0V

Note: 1LSB = 
$$\left(\frac{V_{IN}}{4096}\right)$$

# Bipolar Operation (4-Quadrant Multiplication)

Figure 7 shows the MX7837/MX7847 connected for binary operation. The offset-binary coding is shown in Table 4. When  $V_{\text{IN}}$  is an AC signal, the circuit performs 4-quadrant multiplication. R1, R2, and R3 resistors should be 0.01% ratio matched to maintain gain-error specifications. On the MX7847, the  $R_{\text{FB}}$  feedback resistor is internally connected to  $V_{\text{OUT}}$ .

Table 4. Bipolar Code Table

DAC Latch Contents MSB LSB	Analog Output, VouT
1111 1111 1111	$+V_{IN} \times \left(\frac{2047}{2048}\right)$
1000 0000 0001	$+V_{IN} \times \left(\frac{1}{2048}\right)$
1000 0000 0000	0V
0111 1111 1111	$-V_{IN} \times \left(\frac{1}{2048}\right)$
0000 0000 0000	$-V_{IN} \times \left(\frac{2048}{2048}\right) = -V_{IN}$

Note: 1LSB =  $\left(\frac{V_{IN}}{2048}\right)$ 

### Applications Information

#### **Ground Management**

The use of an uninterrupted ground plane is strongly recommended. AC or transient voltages between analog and digital grounds (between AGNDA/AGNDB and DGND) can inject noise into the analog circuitry. Connect the MX7837/MX7847 AGNDs and DGND directly to the ground plane or to a star ground to ensure that they are at the same potential. In complex systems with separate analog and digital ground planes, connect two diodes (1N914 or equivalent) in inverse parallel between the AGND and DGND pins.

#### Power-Supply Decoupling

To minimize noise, decouple the  $V_{DD}$  and  $V_{SS}$  lines to DGND using a  $10\mu F$  capacitor in parallel with a  $0.1\mu F$  ceramic capacitor. Minimize capacitor lead lengths for best noise rejection.

# Operation with Reduced Power-Supply Voltages

The MX7837/MX7847 are specified for operation with  $V_{DD}/V_{SS} = \pm 11.4 \text{V}$  to  $\pm 16.5 \text{V}$ . However, the output amplifier requires 2.5V of headroom, so the reference input should not come within 2.5V of  $V_{DD}/V_{SS}$  in order to maintain accuracy at full scale.

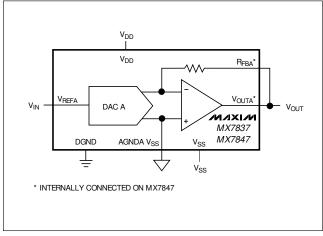


Figure 6. Unipolar Binary Operation

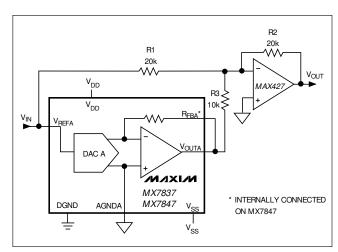
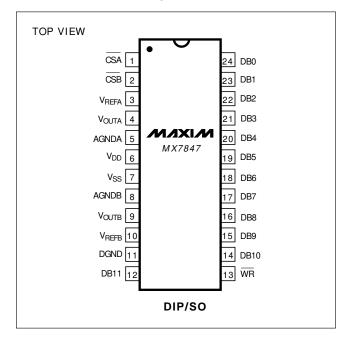
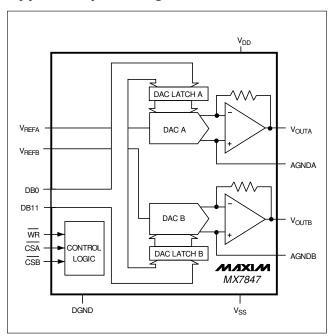


Figure 7. Bipolar Offset Binary Operation

## Pin Configurations (continued)



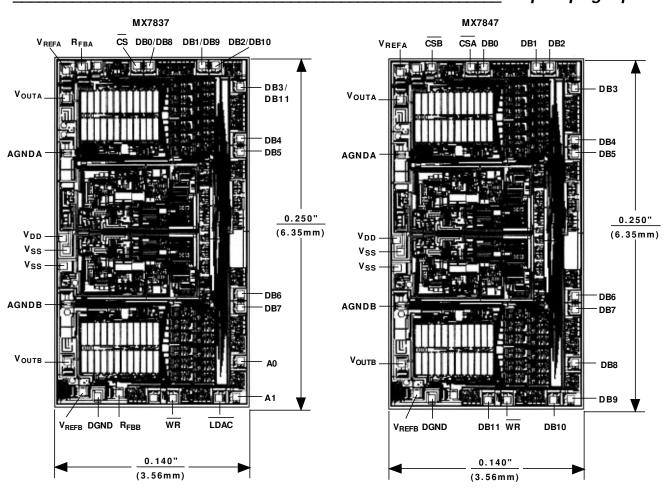
## Typical Operating Circuits (continued)



## \_Ordering Information (continued)

PART	TEMP. RANGE	PIN-PACKAGE	ERROR (LSB)
MX7837AN	-40°C to +85°C	24 Narrow Plastic DIP	±1
MX7837BN	-40°C to +85°C	24 Narrow Plastic DIP	±1/2
MX7837AR	-40°C to +85°C	24 Wide SO	±1
MX7837BR	-40°C to +85°C	24 Wide SO	±1/2
MX7837AQ	-40°C to +85°C	24 Narrow CERDIP	±1
MX7837BQ	-40°C to +85°C	24 Narrow CERDIP	±1/2
MX7837SQ	-55°C to +125°C	24 Narrow CERDIP	±1
MX7837TQ	-55°C to +125°C	24 Narrow CERDIP	±1/2
<b>MX7847</b> JN	0°C to +70°C	24 Narrow Plastic DIP	±1
MX7847KN	0°C to +70°C	24 Narrow Plastic DIP	±1/2
MX7847JR	0°C to +70°C	24 Wide SO	±1
MX7847KR	0°C to +70°C	24 Wide SO	±1/2
MX7847C/D	0°C to +70°C	Dice*	±1
MX7847AN	-40°C to +85°C	24 Narrow Plastic DIP	±1
MX7847BN	-40°C to +85°C	24 Narrow Plastic DIP	±1/2
MX7847AR	-40°C to +85°C	24 Wide SO	±1
MX7847BR	-40°C to +85°C	24 Wide SO	±1/2
MX7847AQ	-40°C to +85°C	24 Narrow CERDIP	±1
MX7847BQ	-40°C to +85°C	24 Narrow CERDIP	±1/2
MX7847SQ	-55°C to +125°C	24 Narrow CERDIP	±1
MX7847TQ	-55°C to +125°C	24 Narrow CERDIP	±1/2

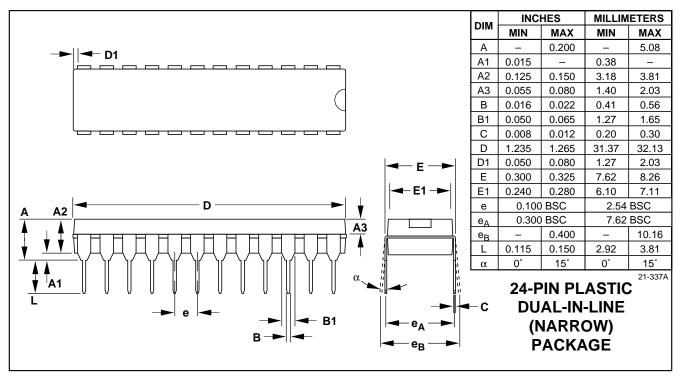
### Chip Topographies

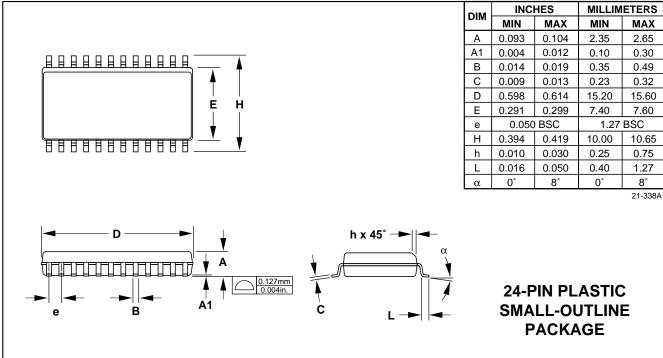


TRANSISTOR COUNT: 1240; SUBSTRATE CONNECTED TO V<sub>DD</sub>.

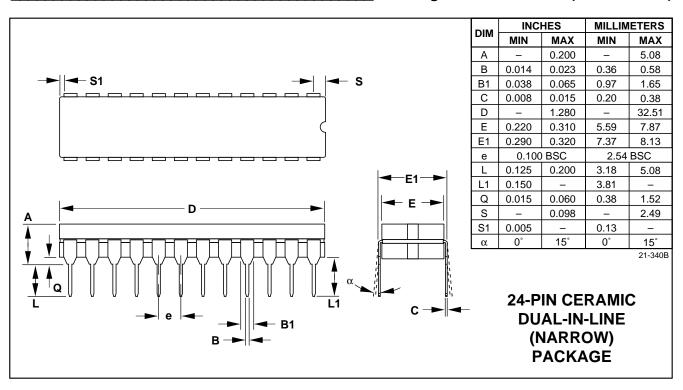
TRANSISTOR COUNT: 1240; SUBSTRATE CONNECTED TO  $V_{DD}$ .

### Package Information





### Package Information (continued)



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